



FOR IMMEDIATE RELEASE

HZO Delivers Cutting-Edge Laser Technology in Providing Protection for Sensitive Circuitry

Breakthroughs in automated material removal improves mass production of waterproof coatings at lower costs and superior quality

RALEIGH, NC – OCTOBER 16, 2019 – [HZO](#), a global leader in delivering world-class protective nano coatings that safeguard electronics from the most demanding corrosive and liquid environments, today unveiled its commercial availability of laser technology and advanced plasma processes for the automated removal of materials critical to enabling protection of electronic assemblies. This latest breakthrough provides multiple options for 2D and 3D inline material removal, reducing overall labor and capital cost, while providing a highly scalable and repeatable manufacturing process.

“Laser Ablation and Plasma Ashing represent the latest in R&D innovation from HZO,” said Zsolt Pulai, Executive VP of Technology & Engineering for HZO. “This technology affords customers the ability to seamlessly and systematically remove coating materials from critical test points and connectors while maintaining the integrity of the protection afforded by thin film coatings like Parylene.”

Combined with HZO’s recently announced PRO750™ GEN4 Coating Chamber, HZO’s ability to apply leading-edge technology for material removal reduces handling, increases throughput, improves accuracy, and delivers a higher quality service to its customers. Savings are derived from reduced capital requirements and materials associated with board-level preparation, as well as lower labor and training demands.

HZO’s new Laser Ablation and Plasma Ashing Equipment enable:

- **Precise and efficient material removal** resulting in improved throughput and higher yields for protected circuitry.
- **Minimally invasive, commercially scalable, proven material management processes** that do not require solvents, oils, or coolants.
- **Increased manufacturing flexibility to achieve superior protection**, including up to IPX8.

Laser Ablation removes coating materials from a solid two-dimensional surface by irradiating it with a laser beam, with extraordinary speed and accuracy. For three dimensional surfaces, HZO employs a process known as Plasma Ashing, capable of removing materials from irregular surfaces through the application of ions and radicals generated by a plasma application

process. Both approaches are safe, environmentally friendly, non-destructive to delicate electronics, and contributes to HZO's extensive intellectual property and patent portfolio.

To learn more about HZO, visit <https://hzo.com/>.

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About HZO Inc.

HZO is a global leader in delivering world-class protective nano coatings that safeguard electronics from the most demanding corrosive and liquid environments. The Company brings together people, process, capital equipment, and material science; leveraging an extensive patent portfolio to create unique solutions to meet specific customer requirements. Working with some of the largest companies across industries including consumer electronics, IoT, medical device and automotive, HZO delivers a better, more reliable, and more durable water-resistant and waterproof product that reduces costly returns, improves customer satisfaction and drives overall brand value. For additional information on HZO, visit www.hzo.com.

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